

ON Semiconductor				10/15/2019
Base Part		KA2904		Pb-free
Orderable Part		KA2904DTF	Total weight (mg)	83.697
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	2.78	Silicon (Si)	7440-21-3	100
Die Attach	0.718	Silver (Ag)	7440-22-4	78.5
		Phenolic Resin-2	54208-63-8	21.5
Lead Frame	38.599	Silver (Ag)	7440-22-4	0.19948703
		Zinc (Zn)	7440-66-6	0.12953703
		Iron (Fe)	7439-89-6	2.39902588
		Copper (Cu)	7440-50-8	97.23308894
		Phosphorus (P)	7723-14-0	0.03886111
Mold Compound-Black	39.401	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8	0.99997462
		Ortho Cresol Novolac Resin	29690-82-2	28.99926398
		Antimony Trioxide (Sb2O3)	1309-64-4	1.99994924
		Carbon Black (C)	1333-86-4	0.75124997
		Fused Silica (SiO2)	60676-86-0	67.24956219
Plating	2	Tin (Sn)	7440-31-5	100
Wire Bond - Au	0.199	Gold (Au)	7440-57-5	100
<p><b>Materials Disclosure Disclaimer:</b> Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p><a href="http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF">http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</a></p>				